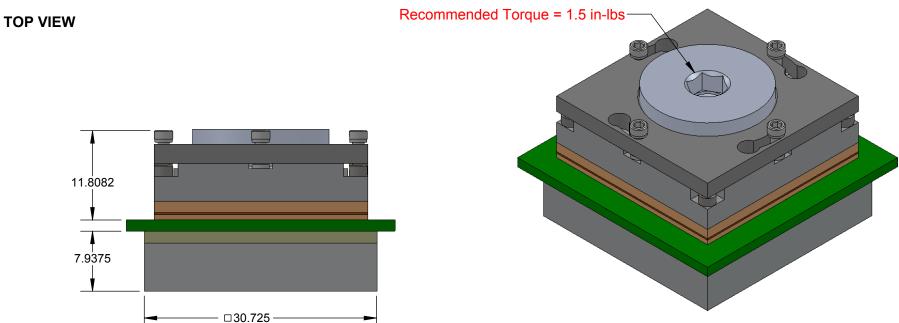


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed, reliable Elastomer connection

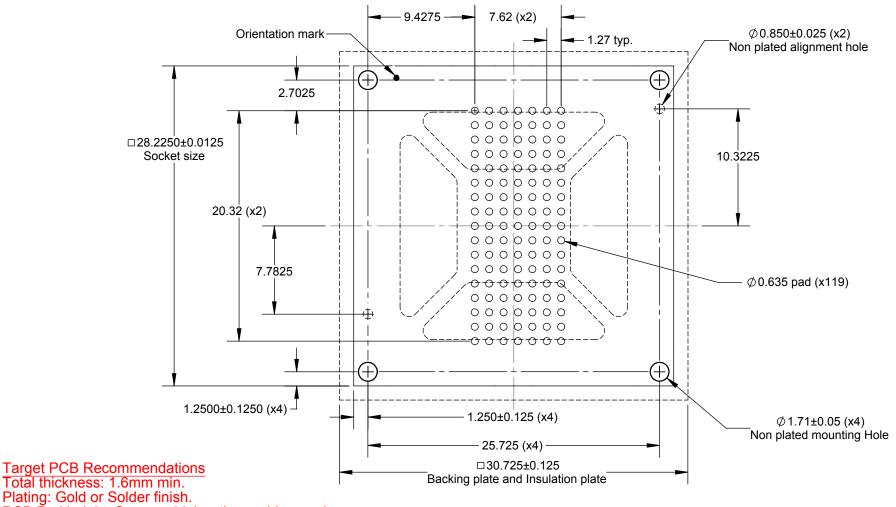
- Minimum real estate required
 Compression plate distributes forces evenly
 Ball guide prevents over compression of elastomer
 Easily removable swivel socket lid



SIDE VIEW

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	SG-BGA-6362 Specification	Material: N/A Finish: N/A Weight: 36.71	STATUS: Released	SHEET: 1 OF 5	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204		DRAWN BY: S. Huang	SCALE: 2:1	
	www.ironwoodelectronics.com		FILE: SG-BGA-6362	DATE: 5/15/2012	



PCB Pad height: Same or higher than solder mask.

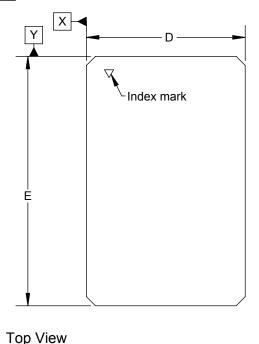
NOTE: Steel backing plate may be required based on end user's application.

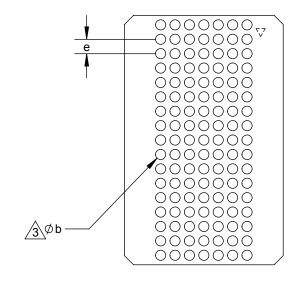
All dimension units are millimeter.

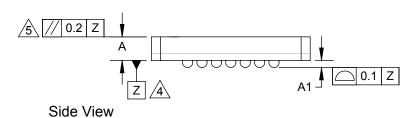
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"], unless stated otherwise.

S	SG-BGA-6362 Specification	cation Material: N/A	STATUS: Released	SHEET: 2 OF 5	REV. A
•	Ironwood Electronics, Inc.	Finish: N/A	DRAWN BY: S. Huang	SCALE: 3:1	I
	Tele: (800) 404-0204 www.ironwoodelectronics.com	FILE: SG-BGA-6362	DATE: 5/15/2012		

Compatible BGA Spec







Bottom View

DIM	MIN	MAX		
Α		2.79		
A1		0.711		
b	0.60	0.90		
D	14.0 BSC			
Е	22.0 BSC			
е	1.0 BSC			

Array: 7x17

Package Code: BGA119A

1. Dimensions are in millimeters.

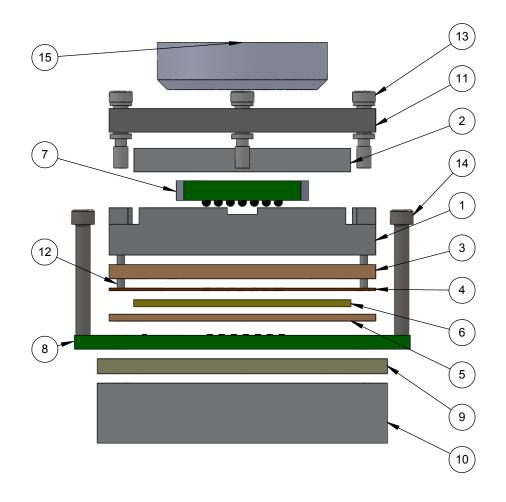
Interpret dimensions and tolerances per ASME Y14.5-1994.

Dimension b is measured at the maximum solder bll diameter, parallel to datum plane Z.

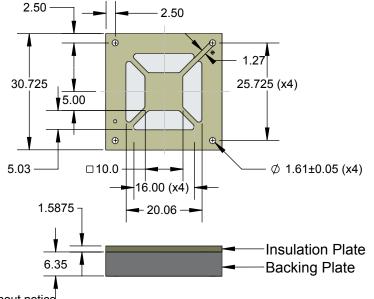
Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

Parallelisml measurement shall exclude any effect of mark on top surface of package.

SG-BGA-6362 Specification		Material: N/A	STATUS: Released	SHEET: 3 OF 5	REV. A
	Ironwood Electronics, Inc. Finish: N/A Tele: (800) 404-0204 Weight: 36.71		DRAWN BY: S. Huang	SCALE: 3:1	
	www.ironwoodelectronics.com	Weight: 36.71	FILE: SG-BGA-6362	DATE: 5/15/2012	



ITEM NO.	DESCRIPTION	Material	
1	SBT Ni Plt socket base, for 23x3mm IC	7075-T6, Plate (SS)	
2	Compression Plate	7075-T6 Aluminum Alloy	
3	IC Guide 14x22mm IC	Ultem 1000	
4	Ball Guide 7x17 array 1.27mm pitch	Kapton Polyimide/Cirlex	
5	Elastomer Guide	Ultem 1000	
6	0.75mm thick 0.1mm pitch 63 deg angled elastomer	Shin-etsu Elastomer	
7	Test Chip	Material <not specified=""></not>	
8	Test PCB	Material <not specified=""></not>	
9	Insulation plate for 23x23mm IC	FR4 High temp	
10	Backing Plate	7075-T6 Aluminum Alloy	
11	Socket Lid	7075-T6 Aluminum Alloy	
12	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel	
13	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)	
14	#0-80 x 0.5, SH Cap Screw	Material <not specified=""></not>	
15	Compression Screw, M18	7075-T6 Aluminum Alloy	



Description: SK Assem and B P w/ Ins P

All dimension units are millimeters.

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

SG-BGA-6362 Specification

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 36.71

STATUS: Released	SHEET: 4 OF 5	REV. A
DRAWN BY: S. Huang	SCALE: 2.5:1	
FILE: SG-BGA-6362	DATE: 5/15/2012	

Rev	Date	Initials	ECO	Description
Α	-	-		Original

Description: Revision History

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6362 Specification	Material: Finish: Weight:	STATUS: Released	SHEET: 5 OF 5	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204		DRAWN BY: S. Huang	SCALE: 2:1	
www.ironwoodelectronics.com		FILE: SG-BGA-6362	DATE: 5/15/2012	